WW.Dathiutson Industries



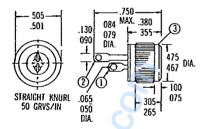


PRESS FIT SERIES SCR's

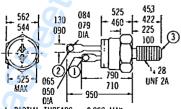
8 AMPERE CENTER GATE 10 AMPERE CENTER GATE 20 AMPERE CENTER GATE 25 AMPERE CENTER GATE 35 AMPERE CENTER GATE

Hutson's SCR's feature proprietary, void-free glass passivated chips and are hermetically sealed to eliminate "punch through" and "burn through" which are associated with organic passivation materials.

SCR's are available in current ratings to 40 amperes and voltage (VDRM) ratings to 800 volts. These economical and highly reliable SCR's are the result of Hutson's advanced engineering and manufacturing technology, state-of-the-art glass passivation materials and techniques and experience in switching devices application.



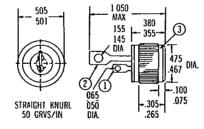
½" PRESS FIT (1) TO-203



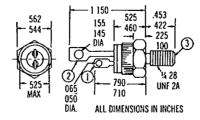
1 PARTIAL THREADS = 0 909 MAX
2 UNITS SHALL NOT BE DAMAGED BY
30 INCH POUNDS TORQUE APPLIED TO
CLASS 28 NUT ASSEMBLED ON THREADS

3 MAX PITCH DIA OF PLATED THREADS SHALL BE (0 2268) (REF ASA STD NR 811 1960)

1/2" STUD MOUNT (2) MOD. TO-48

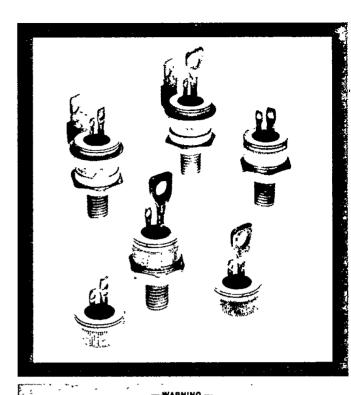


1/2" PRESS FIT (1) TO-203 (MOD)



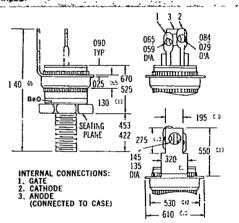
- 1 PARTIAL THREADS = 0 909 MAX
- 2 UNITS SHALL NOT BE DAMAGED BY 30 INCH POUNDS TORQUE APPLIED TO CLASS 28 NUT ASSEMBLED ON THREADS
- 3 MAX PITCH DIA OF PLATED THREADS SHALL BE (0 2268) (REF ASA STD 'NR B11-1960)

1/2" STUD MOUNT (2) MOD. TO-48



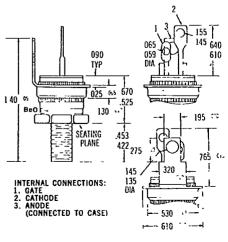
isolated slud products should be handled with care. The ceramic sused in those thyristors contains BERYLLIUM OXIDE as a major ingredient.

DO NOT crush, grind, or abrade these portions of the thyristors because the dust resulting from such action may be HAZARDOUS II INHALED.



ALL DIMENSIONS IN INCHES

1/2" ISOLATED STUD MOUNT



ALL DIMENSIONS IN INCHES

1/2" ISOLATED STUD MOUNT

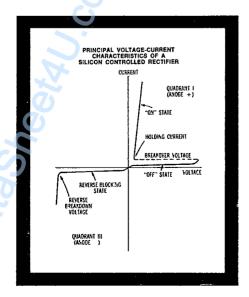
www.Data	\$heet4U.com	SYMBOL	V _{DRM} AND V _{RRM} .	DEVICE NUMBERS	
MAXIMUM RATINGS	Repetitive Peak Off-State Voltage and Repetitive Peak Reverse Voltage at T _J = 100°C ★ Note: 800 Volts Available in Some Series	V _{DRM} AND V _{RRM}	50 100 200 300 400 500 600	S08 S18 S28 S38 S48 S58 S68	\$010 \$110 \$210 \$310 \$410 \$510 \$610
	RMS On-State Current at T _C = 75°C	I _(RMS)	-	8	10
	Peak Surge (Non-Repetitive) On-State Current, One Cycle at 50 Hz or 60 Hz	I _{TSM}		80	100
	Peak Gate-Trigger Current for 3 μsec. Max.	I_{GTM}		20	20
	Peak Gate-Power Dissipation at $I_{GT} \le I_{GTM}$ for 3 μ sec. Max.	P_{GM}		20	20
	Average Gate-Power Dissipation	P _{G(AV)}		0.5	0.5
	Storage Temperature Range	$T_{\mathtt{STG}}$		-40 to +150	
	Operating Temperature Range	T _{oper}		40 to +100	
ELECTRICAL CHARACTERISTICS At Maximum Ratings and Specified Case Temperatures	Peak-Off State Current at $T_J = 100^{\circ}$ C, Gate Open and V_{DRM} and $V_{RRM} = Max$. Rating	I _{DRM} and I _{RRM}		2.0 Max.	2.0 Max.
	Maximum On-State Voltage (Peak) Tc = 25°C	V_{TM}		2.5 Max.	2,0 Max.
	1	State Current		16	20
	DC Holding Current at T _c = 25°C (Gate Open)	I _{HO}		50 Max.	50 Max.
	DC Gate-Trigger Current for Anode Voltage =12 VDC; R_L = 30 Ω and at T_C = 25°C	l _{GT}		25 Max.	25 Max.
	DC Gate-Trigger Voltage for Anode Voltage = 12 VDC; $R_L = 30 \Omega$ and at $T_C = 25^{\circ}C$	V_{GT}		2.0 Max.	2.0 Max.
	Gate Controlled Turn-On Time to + ts let = 150 mA	$T_{\scriptscriptstyle ext{GT}}$		2.5 (Typ.)	2.5 (Typ.)
	Critical Rate-of-Rise of Off-State Voltage (Gate Open) and $T_c = 100^{\circ}$ C	Critical dv/dt		100 (Typ.)	100 (Typ.)
At M	Thermal Resistance, Junction to Case	R _{ejc}	Pressfit Stud Isolated Stud	2.5 (Typ.) 3.0 (Typ.) 3.2 (Typ.)	2.5 (Typ.) 3.0 (Typ.) 3.2 (Typ.)

INSTALLATION INSTRUCTIONS 1/2" PRESS FIT SCR's

- 1. Recommended Heat Sink material: Copper (recommended for maximum heat transfer and minimum corrosion problem), aluminum or steel.
- 2. Heat sink should be 1/8" thick minimum.
- 3. The hole diameter into which the SCR is pressed must be 0.4975 ± .001 inch. A slight chamfer on the hole should be used. This hole may be punched and reamed in a flat plate or extruded and sized in sheet metal.
- 4. The entire knurled section of the SCR should be in contact with the heat sink to insure maximum heat transfer. The SCR must not be inserted into a heat sink deeper than the knurl height.
- 5. The SCR insertion force must not exceed 800 pounds. If the insertion force approaches that value either the SCR is misaligned with the hole or the SCR-to-hole interference is excessive. The insertion force must be uniformly applied to the top face (terminal end) of the SCR within an annular ring which has an inside diameter not less than 0.370 inch and not larger than 0.390 inch; the outside diameter must not be less than 0.500 inch.
- 6. The thermal resistance between the SCR case and a copper heat sink should not exceed 0.5° C/W if the SCR is inserted in the manner described above.

 PFSS -0000 B-2X

ww.DataSheet4U.col	UNITS		
\$020 \$120 \$220 \$320 \$420 \$520 \$620	\$025 \$125 \$225 \$325 \$425 \$525 \$625	\$035 \$135 \$235 \$335 \$435 \$535 \$635	VOLTS
20	· 25	35	AMP
200	250	350	АМР
20	20	20	AMP
20	20	20	WAT,T
0.5	0.5	0.5	WATT
	°C		
	°C		
2.0 Max.	2.0 Max.	2.0 Max.	mA
1.9 Max.	1.5 Max.	1.6 Max	VOLTS
40	50	70	AMPS
50 Max.	50 Max.	50 Max.	mA
25 Max.	25 Max.	25 Max.	mA
2.0 Max.	2.0 Max.	2.0 Max.	VOLTS
2.5 (Typ.) .	2.5 (Typ.)	2.5 (Typ.)	μsec
100 (Typ.)	100 (Typ.)	100 (Typ.)	V/ _{μsec}
1.3 (Typ.) 1.8 (Typ.) 2.0 (Typ.)	1.3 (Typ.) 1.8 (Typ.) 2.0 (Typ.)	0.9 (Typ.) 1.4 (Typ.) 1.6 (Typ.)	°C/ _{WATT}



SCŘ's

Non Repetitive Peak Reverse Voltage (Open Gate) - VRSOM - The maximum instantanous value of any non-repetitive transient reverse voltage which occurs across an SCR whose gate is open.

Repetitive Peak Reverse Voltage (Open Gate) - VRROM - The maximum instantaneous value of the reverse voltage which may be applied across an SCR, including all repetitive transient voltages, but excluding all nonrepetitive transient voltages, when the gate is open.

Repetitive Peak Off-State Voltage (Open Gate) — V_{DROM} — The maximum instantaneous value of the off-state voltage which may be applied across an SCR (when the gate is open), including all repetitive transient voltages, but excluding all non-repetitive transient voltages.

Average On-State Current — $I_{\mathbf{T}(AV)}$ — The principal current, DC value with alternating component, when an SCR is in the on-state.

RMS On-State Current — $I_{\rm T(RMS)}$ — The principal current, total RMS value, when an SCR is in the on-state.

Surge (Non-Repetitive) On-State Current — I_{TSM} — An on-state current of short-time duration and specified waveshape.

Rate of Change of On-State Current - di_T/dt - The maximum value of the rate-of-rise of on-state current which an SCR can withstand without deleterious effect.

Peak On-State or Off-State Gate Power Dissipation — $P_{\rm GM}$ — The peak instantaneous power dissipated between gate and cathode, of a reverse blocking thyristor.

Average On-State or Off-State Gate Power Dissipation - PG(AV) - The average power dissipated between gate and cathode of a reverse blocking thyristor.

Instantaneous Forward Breakover Voltage (Open Gate) - VFGROOD - The instantaneous principal voltage at the breakover point with the gate open.

Peak Off-State Current (Open Gate) - Ipon - The maximum principal current when an SCR is in the off-state.

Repetitive Peak Reverse Current (Open Gate) - IRROW - The peak instantanous reverse current when the SCR is in the reverse blocking state.

Instantaneous On-State Voltage — v_T — The instantaneous principal voltage when the SCR is in the on-state.

Average Trigger Current - I at - The minimum gate current, DC value. required to switch an SCR from the off-state to the on-state.

Average Trigger Voltage - VGT - The minimum gate-to-cathode voltage, DC value, required to produce the gate trigger current.

Instantaneous Holding Current - in - The instantaneous minimum principal current required to maintain the SCR in the on-state.

Instantaneous On-State Current - IT - The instantaneous value of the principal current for a positive anode-to-cathode voltage

Critical Rate of Applied Forward Voltage — Critical dv/dt — The minimum value of the rate of applied forward voltage which will cause the thyristor to switch from the off-state to the on-state.

Gate Controlled Turn-On Time — $t_{\rm gt}$ — The time interval between a specified point at the beginning of the gate pulse and the instant when the principal voltage has dropped to a specified low value (or current has risen to a specified high value) during switching of an SCR from off-state to the on-state by a gate pulse.



HUTSON INDUSTRIES

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PFSS - 00008-3X

